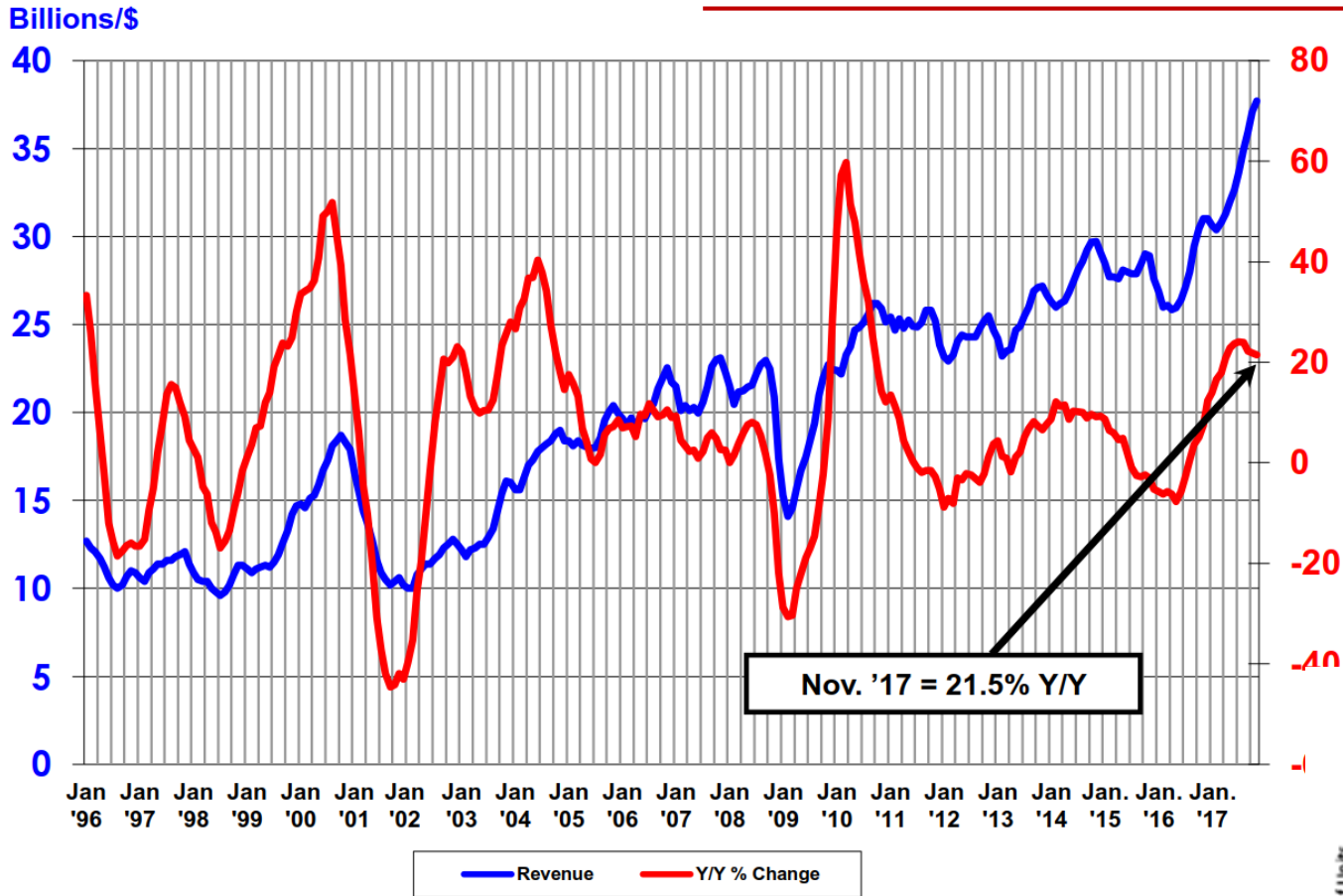


IT Technology and Markets, Status and Evolution

General Semiconductor Market



Source: WSTS

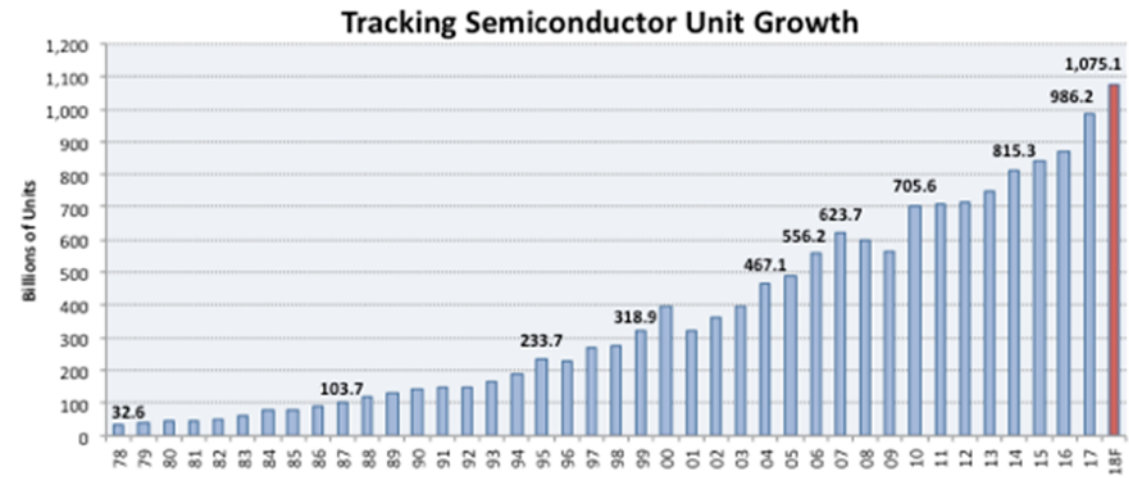
Total IT spending expected in 2018: 3.7 trillion \$, 4.5% growth rate

Wafer supply companies have increased prices in 2017 and will increase by 20% in 2018 and further in 2019

Large jump (21.5%) in revenue and growth rate in 2017 which will partly continue in 2018
Major reason: RAM price increase by 120%

Total revenue per year has now crossed 400 B

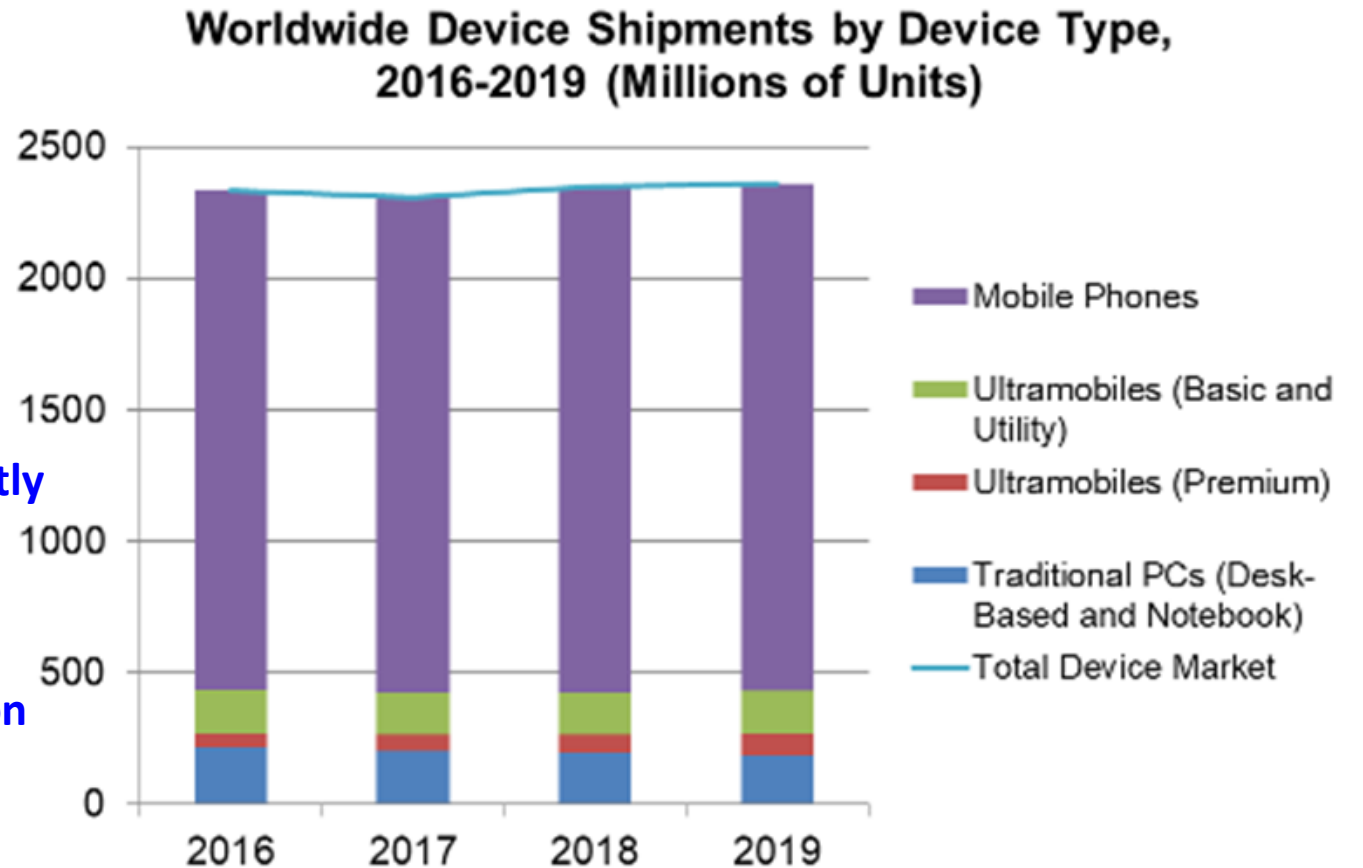
Biggest semiconductor company is now Samsung (61 B\$), followed by Intel (58 B\$)
10 companies make >50% of revenues



More than 1 trillion semiconductor units will be shipped in 2018 (12% are microprocessors, DRAM, NAND, etc)

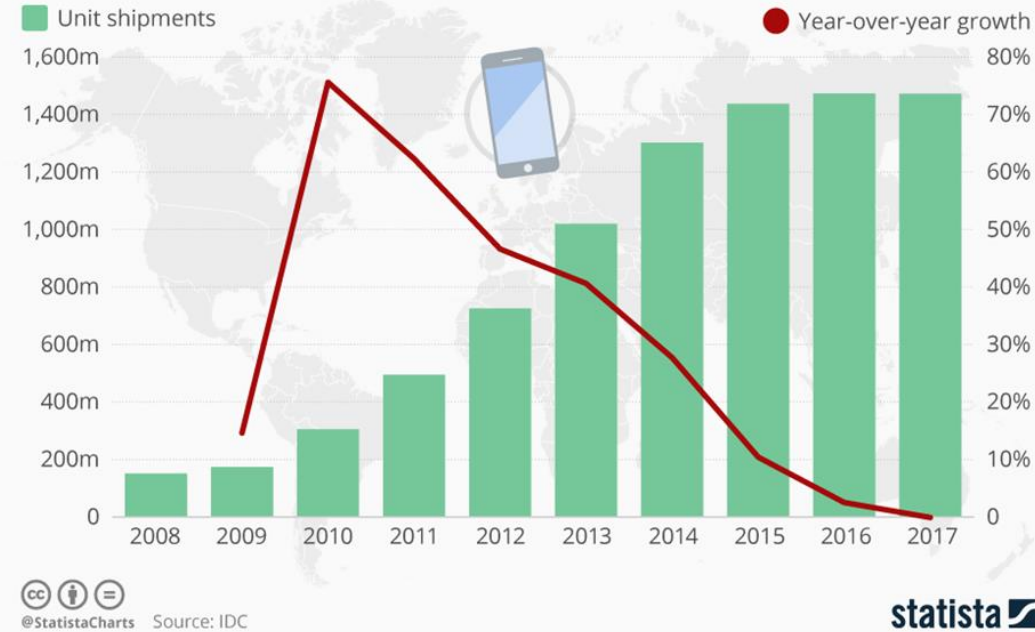
Device Markets

Overall Computing Device market is flat, becomes replacement market



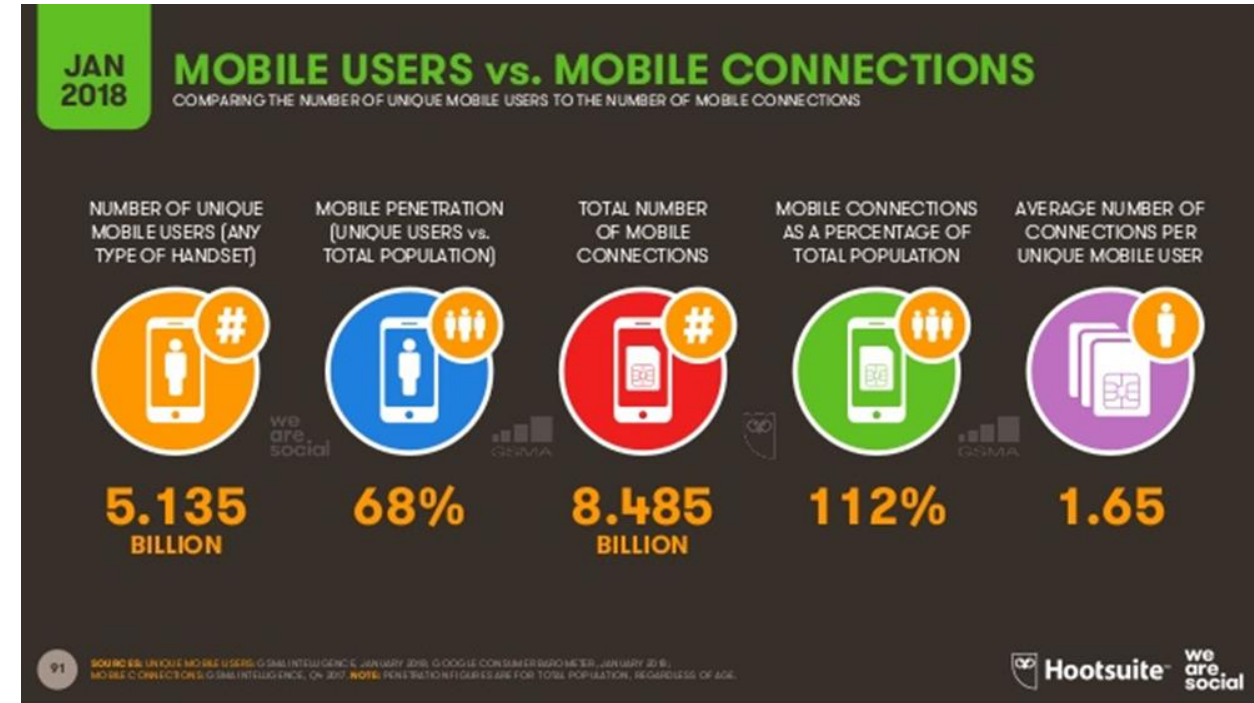
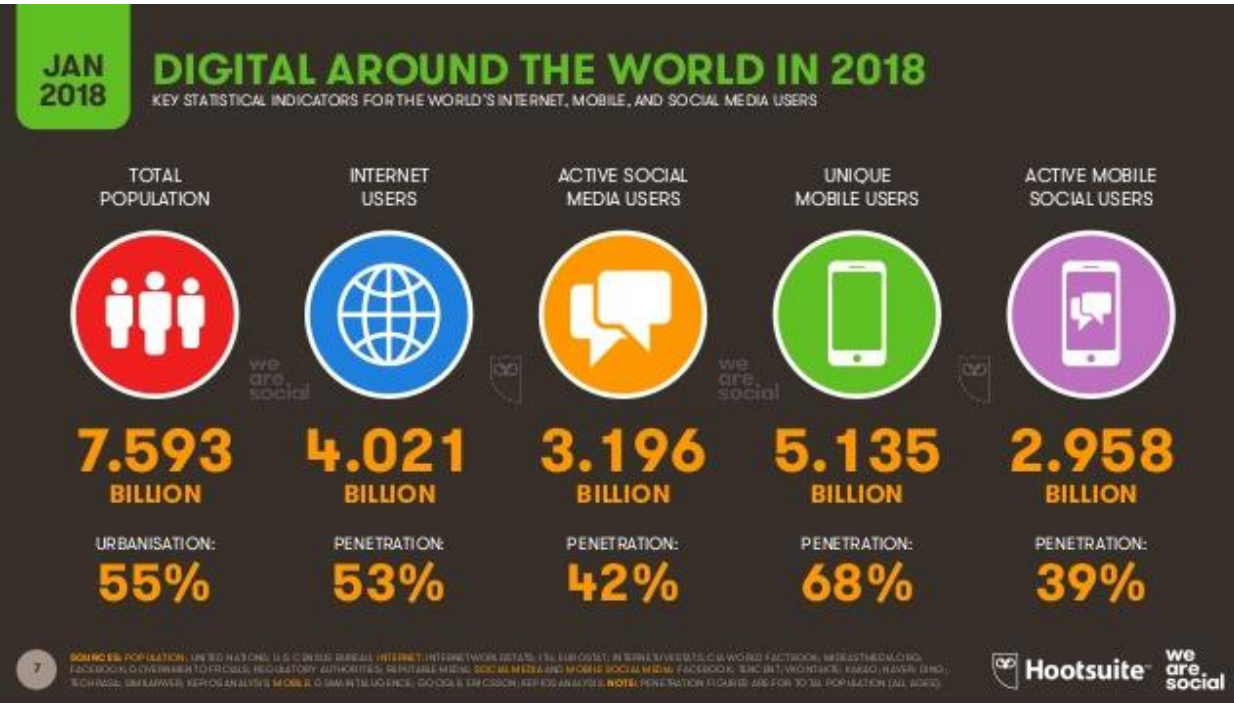
Have We Reached Peak Smartphone?

Worldwide smartphone shipments and year-over-year shipment growth



- PCs, notebooks and tablets sales declining constantly
- Smartphones sales are flat
- Attractiveness of replacement is decreasing
- Only marginal differences between smartphone models and generations, small and little innovation
- Lifetime increase

World Internet Population

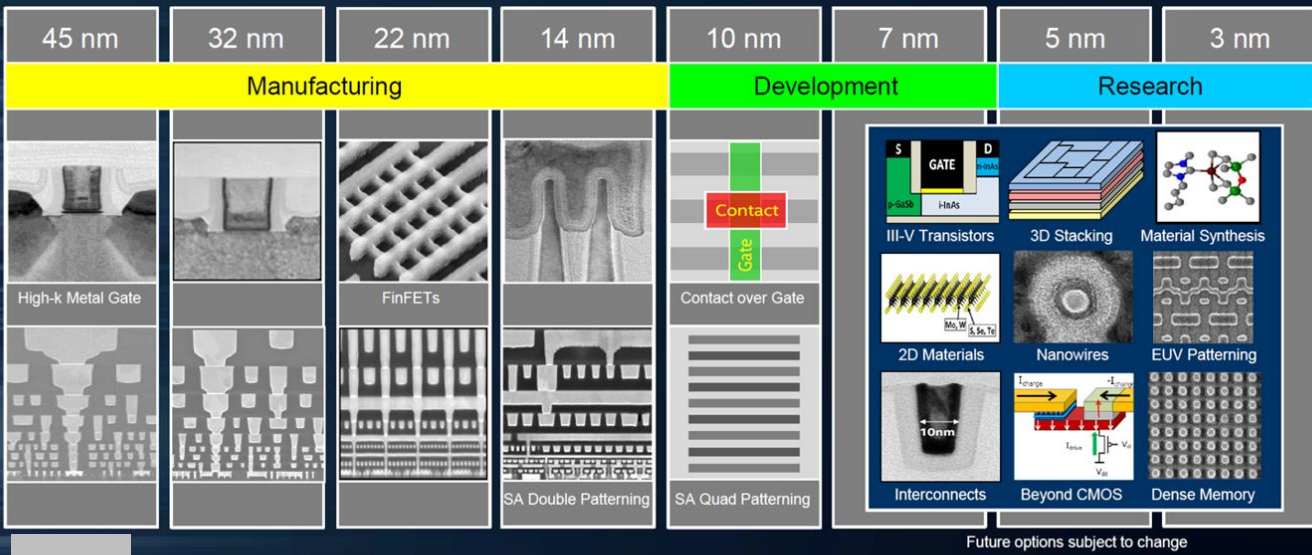


Saturation effects

Limited growth rates for internet devices due to limited growth rate of internet users

Already high market penetration in the population

68% of the world population have a phone



Processor Technology

Intel has problems with their 10nm process

TSMC building fab 18 for their 5nm process, Will be finished in 2020; 950000 m2 for 17 B\$

There is no norm for the process names: 10 nm Intel compares to a 7 nm Samsung/TSMC process

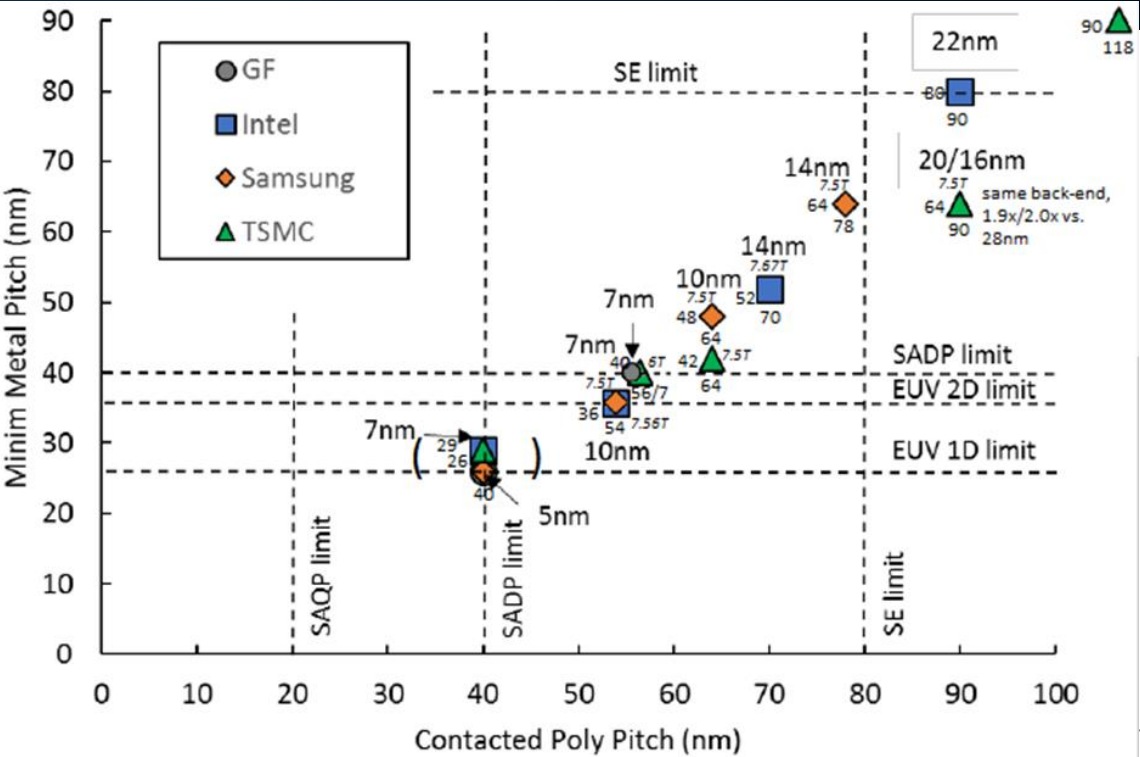
Below 7nm new technologies are needed (nanowires, non-silicon materials), very expensive

Intel We have a wide range of options in research to continue Moore's Law

Industry FinFET Lithography Roadmap, HVM Start
Data announced by companies during conference calls, press briefings and in press releases

	2016	2017		2018		2019		2020		2021
		1H	2H	1H	2H	1H	2H	1H	2H	
GlobalFoundries		14LPP		7nm DUV		7nm with EUV*				
Intel	14 nm 14 nm+	14 nm++ 10 nm		10 nm+ 10 nm++						
Samsung	14LPP 14LPC	10LPE		10LPP		8LPP 10LPU		7LPP 6 nm* (?)		
SMIC	28 nm**		14 nm in development							
TSMC	CLN16FF+ CLN16FFC		CLN10FF CLN16FFC		CLN7FF CLN12FFC		CLN12FFC/ CLN12ULP		CLN7FF+ 5 nm* (?)	
UMC	28 nm**		14nm		no data					

*Exact timing not announced
**Planar

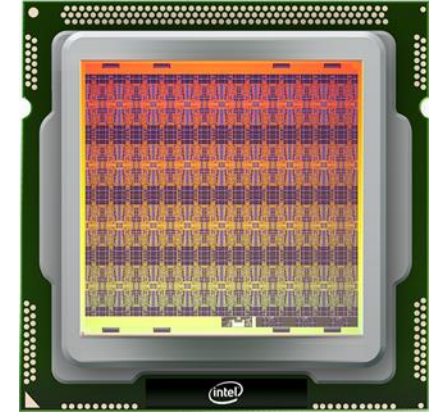


ner-Steind

New Processor Architectures

There is a plethora of new processor designs, all with a focus on Machine Learning:

- Intel: Mobileye EyeQ5 (vision processing, autonomous cars), Nervana Neural Network Processor, Movidius MyriadX VPU
- ARM: Project Trillium, Machine Learning processor, Object Detection processor
- Graphcore IPU (Intelligent Processing Unit)
- Google second generation of Tensor Processing Unit TPU
- NeuPro AI processor from CEVA
- Neuromorphic chips from IBM (TrueNorth, 64 M neurons + 16 B synapsis) and Intel (Loihi, 130 K neurons + 130 M synapsis)
- Nvidia is enhancing their graphics cards, Titan V (110 Tflops Deep Learning), Xavier (SoC, 20 TOPS, vision accelerator)



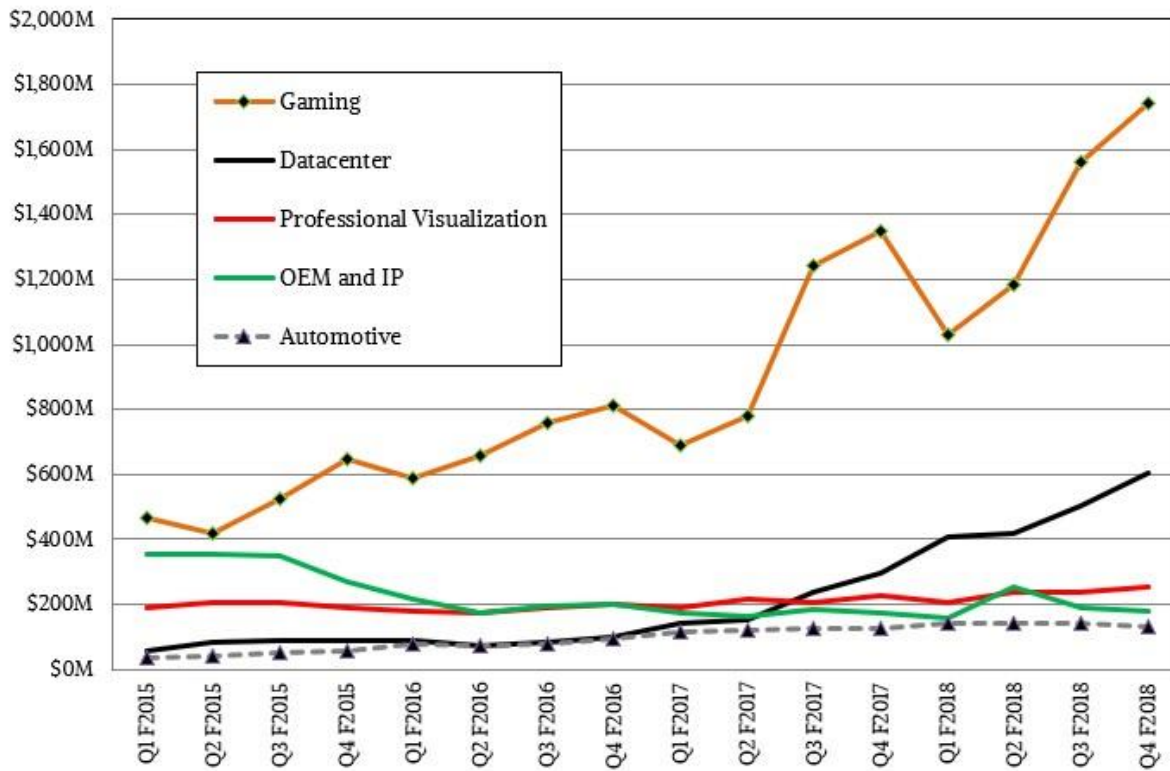
All high-end smartphones are integrating AI chip enhancements (Qualcomm-neural processing engine, Apple- A11 Bionic chip, etc.)
The market for these special chips will reach 5-10 B\$ in 2022

The keyword is LOCAL data processing also major impact on IoT
→ much less network, cloud storage and cloud processing needed

Accelerators

GPUs

- Dedicated Graphics Cards market leader in Nvidia
- High end card Tesla V100 (14 TFlops SP, 110 Tflops ML, 12nm process)
- Gaming key driver for the market (plus AI and crypto mining).
- Large price increases (up to x2), crypto mining + high memory prices
- Change license policy → no gamer cards in the center
(GTX 1080 TI = 700\$ → Tesla V100 9000\$, but also DP performance 20-30 higher)



other accelerators:

- Intel stopped the Xeon Phi line (Knights Mill last product)
Not clear what the replacement will be
- Microsoft Project brainwave, based on Intel (Altera) Stratix FPGA
- Xilinx ACAP, Project Everest many-core SoC, programmable DSPs
50 B transistors, TSMC 7nm process
- Chinese Matrix-2000 DSP accelerator for Exascale HPC
(current No 1 supercomputer)

1 B PC gamer worldwide

PC gaming hardware market 35 B\$, total gaming market 165 B\$

Quantum Computing

Considerable progress during the last 2 years. Number of qubits sharply rising

→ Intel 49-qubit, IBM 50, Google 72 for a Quantum gate computer

→ D-wave 2000 qubits, but not a general quantum computer (e.g. no shor's algorithm, no factorization)

Various implementations from Ion traps to silicon, focus is on silicon to re-use the fabrication process of standard chips

Coherence time is still well below 1 ms, limits the time for quantum calculations

Key problem is the Error handling:

Mitigate by combining qubits

- N physical qubits == one logical qubit, where N varies between 10 and 10000

- Use error correction in software, deal with approximative results

Machine learning algorithms

The Programming model is completely new; not clear how many algorithm can be 'converted' for a quantum computer;

Very, very high cost structure

→ prognosis: Irrelevant for HL-LHC



Optical Computing

Renaissance of optical computing, this time focused on neural networks

- Optalysis First implementation of a Convolutional Neural Network with Optical Processing Technology

- Lightelligence Deep learning with coherent nanophotonics circuits

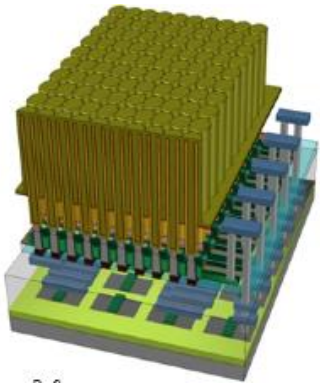
- Lightmatter Photonics for AI

DRAM Roadmap Plan vs. Reality

DRAM Technology Review

TECHINSIGHTS

■ DRAM Process Node Roadmap (Manufacturers)



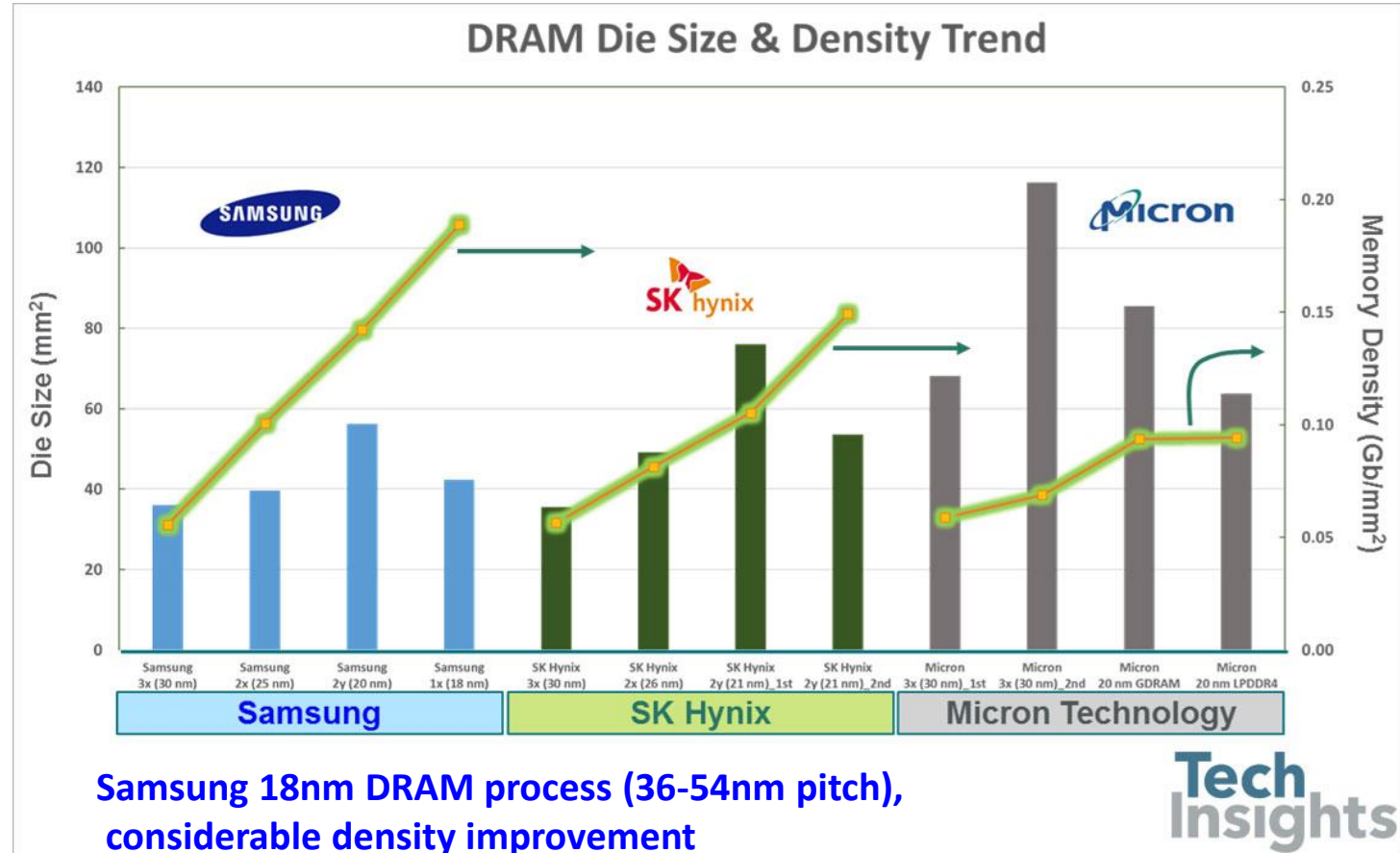
DRAM scaling slowed down
Capacitor aspect ratio increases exponentially with smaller cell size
→ much higher Fabrication costs

3D DRAM not yet available

DRAM Memory

~70 B\$ market

DRAM price increase during the last 18 month: ~120%
Trend to increase a further 5-10% in 2018



Samsung 18nm DRAM process (36-54nm pitch), considerable density improvement
But it is linear not exponential !

Tech Insights

New Memory Technologies

Technology Comparison



Technology	FeRAM	MRAM	ReRAM	PCM	DRAM	NAND Flash
Nonvolatile	Yes	Yes	Yes	Yes	No	Yes
Endurance	10^{12}	10^{12}	10^6	10^8	10^{15}	10^3
Write Time	100ns	~10ns	~50ns	~75ns	10ns	10 μ s
Read Time	70ns	10ns	10ns	20ns	10ns	25 μ s
Power Consumption	Low	Medium/Low	Low	Medium	Very High	Very High
Cell Size (f ²)	15-20	6-12	6-12	1-4	6-10	4
Cost (\$/Gb)	\$10/Gb	\$30-70/Gb	Currently High	\$0.16/Gb	\$0.6/Gb	\$0.03/Gb

Several contenders for a new memory technology
Ideally replacing DRAM and NAND at the same time.

No cost effective solution yet.

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14

**Resistive RAM, 40nm process, Fujitsu/Panasonic
Aimed at Neuromorphic Computing**

Magnetic RAM, 80nm process , Everspin, first 1-2GB SSDs

PCM Intel Optane, in production, but focus not clear

Ferroelectric RAM, very small scale products, difficult to scale

NAND Storage

- 60 B\$ market
- Fabrication moved from 2D to 3D, 64 layers in the market, 96 layer production started, 128 layers expected for 2020
- NAND prices increased over the last 18 month, high request for smartphones and SSDs (Apple busy 20% of the world-wide NANDs), now 50% of all sold NAND chip are 3D, in 2017 the largest consumer of NAND chips were SSDs (surpassing smartphones)
- 2018 price trend not clear +/- 5-10% price in- or decrease → 4 new Chinese fabs will start production this year
- 4-bit cells are now feasible with 3D : ECC code easier with 2D cell size increased ; lab demos exist with hundreds of layers
- investment 3D fabrication process is up to 5x higher than 2 D, ~10B\$ for fabrication facility
- Technical challenges: > 64 layers show exponential scaling problems (current density, cell uniformity)
a wafer stays up to 3 month in the fab before the 100 defect-free layers are done
- Density improvements are now linear, adding 8/16/32 layers

Figure: NAND Flash Factories Map in 2020



Source: DRAMeXchange, Jan., 2018

Hard Disk Storage I

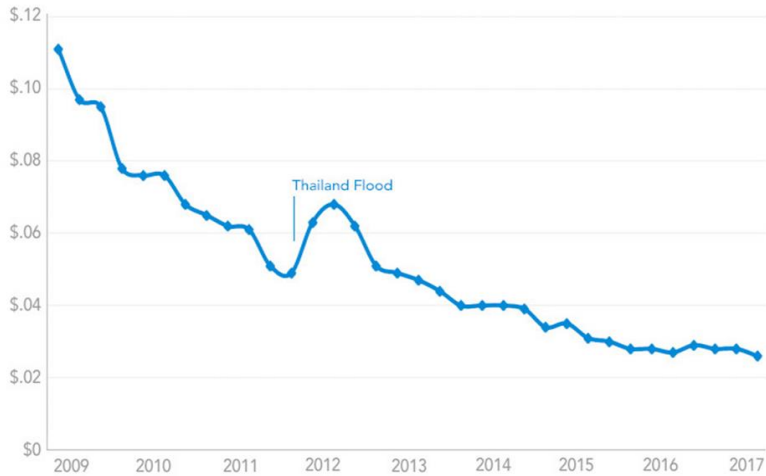
Backblaze Average Cost per Drive Size

By Quarter: Q1 2009 - Q2 2017

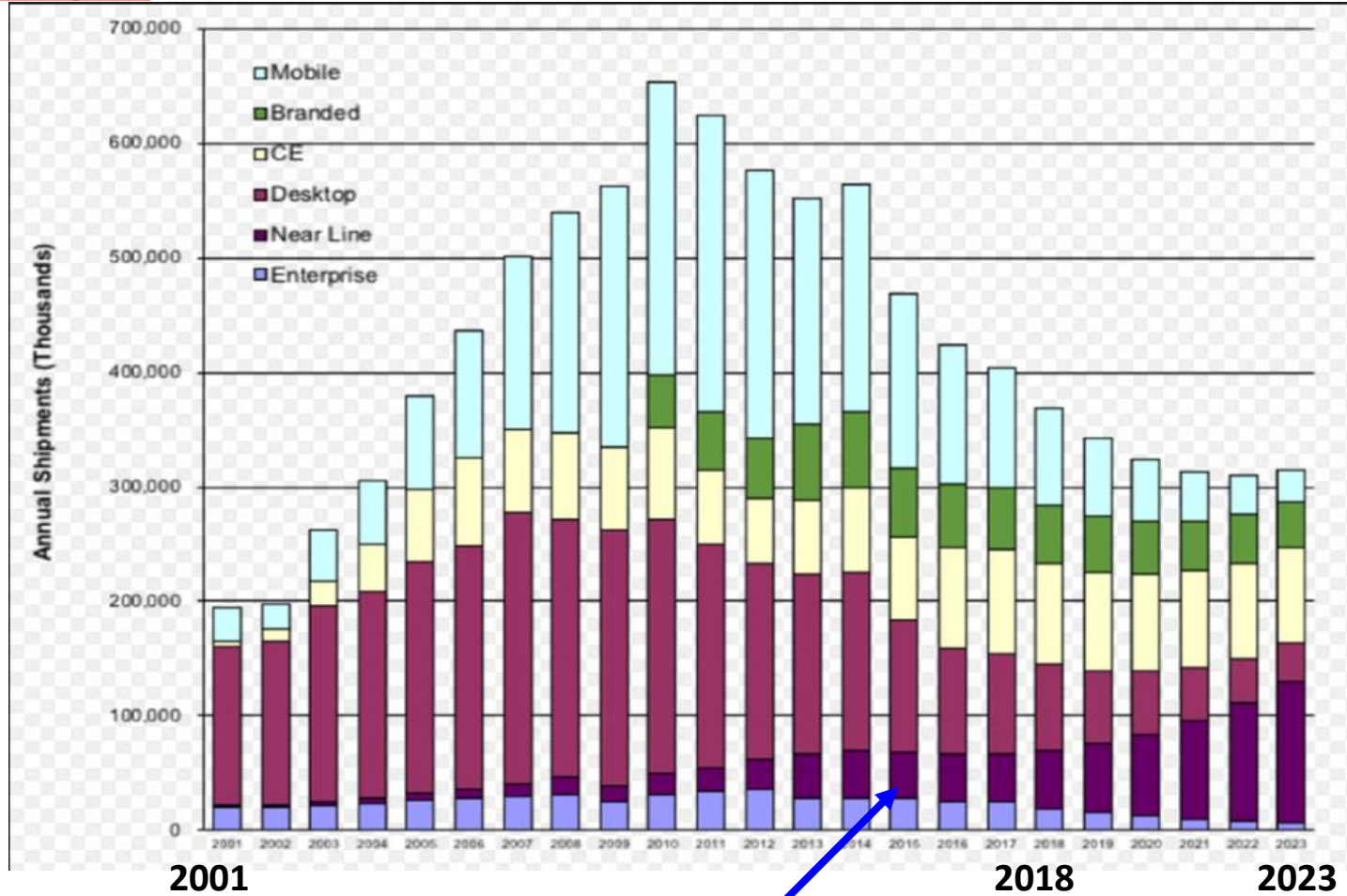


Backblaze Average Cost per GB for Hard Drives

By Quarter: Q1 2009 - Q2 2017



20. IVIATU 2010

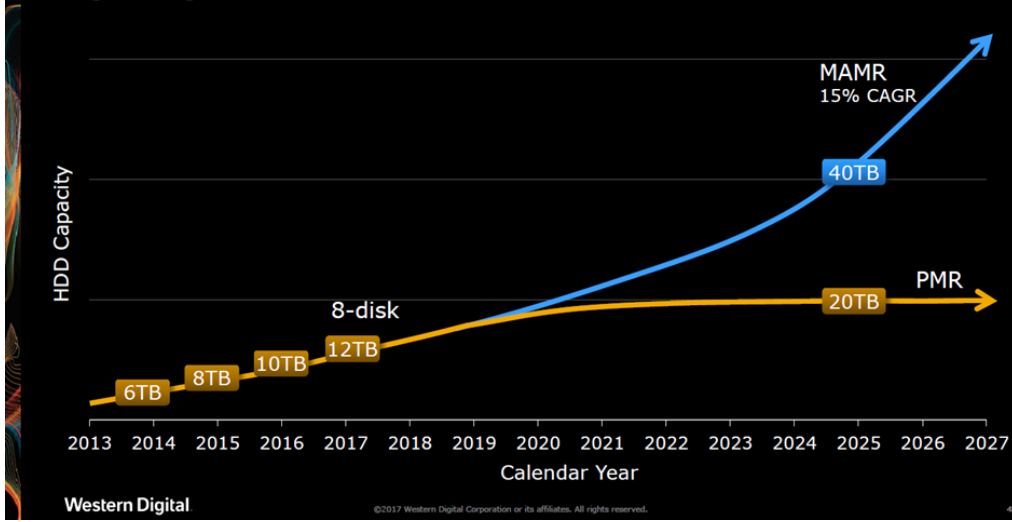


Only growth rate in Near Line disks (high capacity), HEP and Cloud Storage area

Desktop, Mobile, Enterprise replaced by SSDs

Price/space evolution flattening

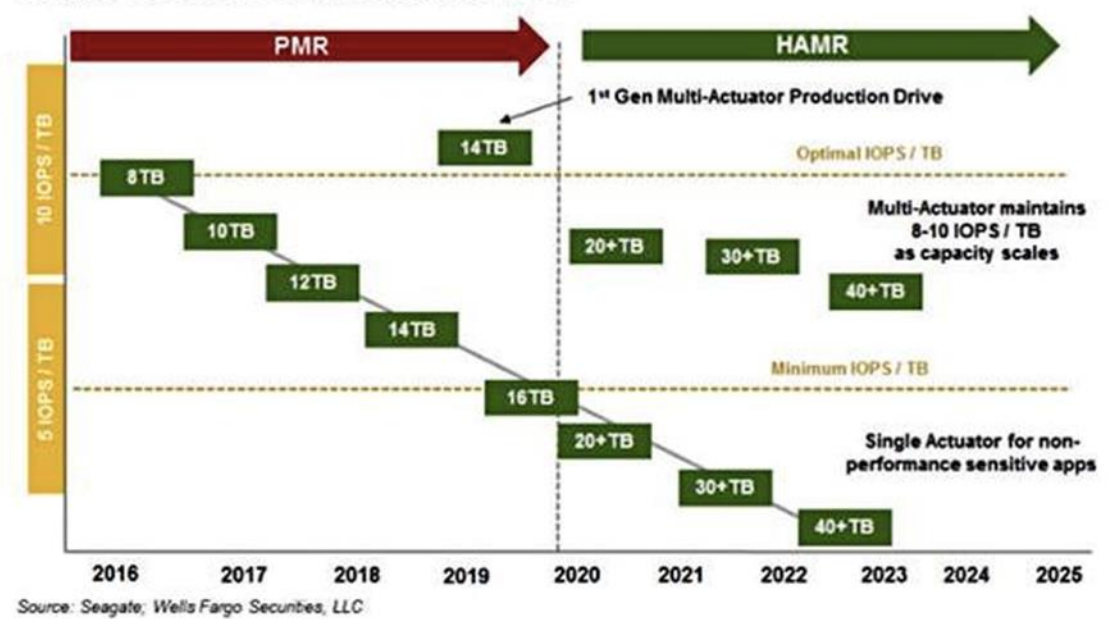
Capacity Growth Outlook



9 platter in one disk 14 TB capacity today He filled
Max with SMR is probably around 20 TB per HDD

Hard Disk Storage II

Seagate Roadmap for Multi-Actuator HDDs

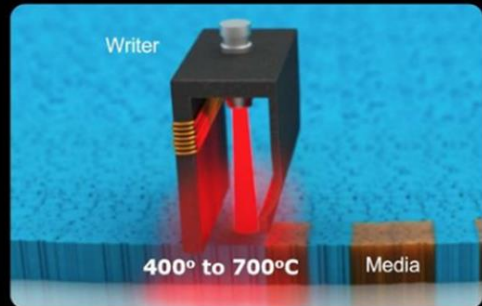


Seagate: multiple actuators per HDD to keep IOPS/TB constant

Seagate HAMR first products now in 2020

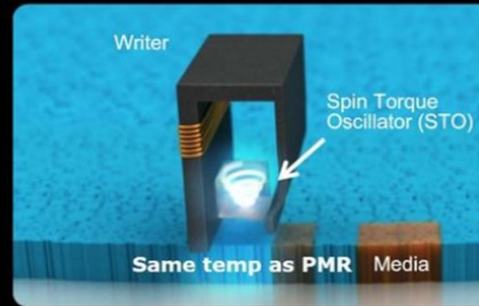
Western Digital new density approach: MAMR production in 2019

How HAMR Works

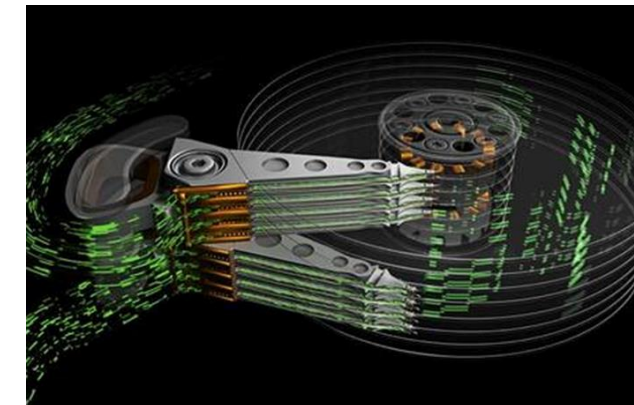


- Heat from laser lowers the energy barrier to write on media and magnets can be switched with smaller magnetic field
- When media cools, the data is harder to erase

How MAMR Works

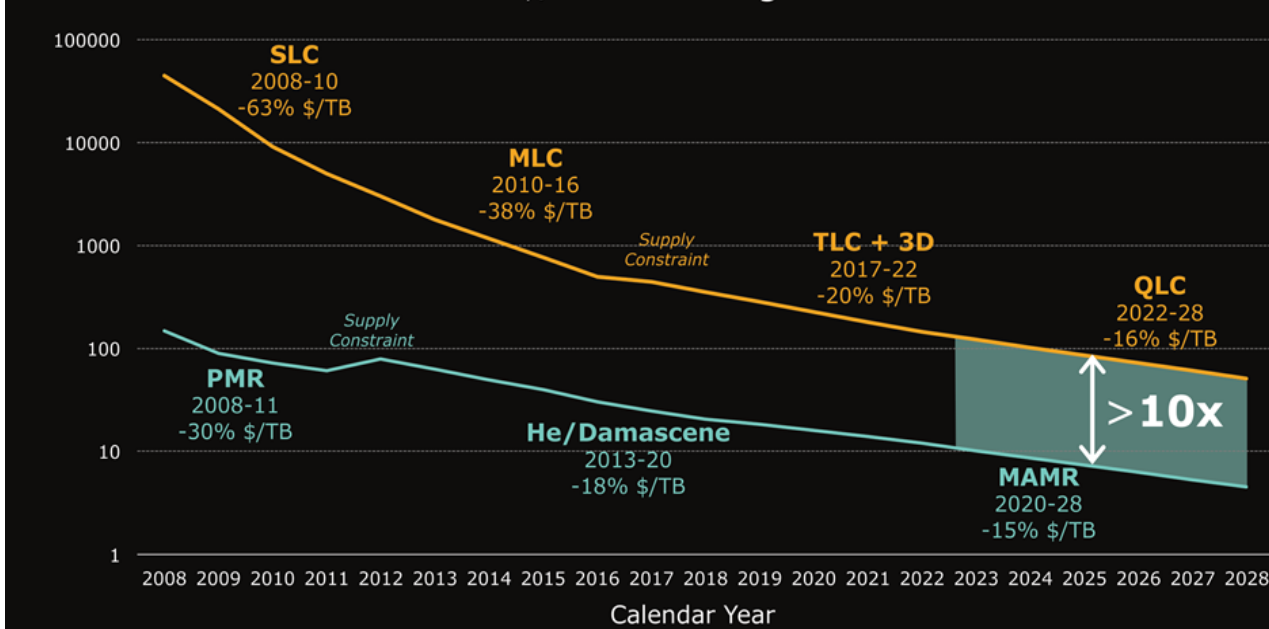


- Microwave fields emitted by a Spin Torque Oscillator (STO) located near the write pole allows writing of perpendicular media at lower magnetic fields



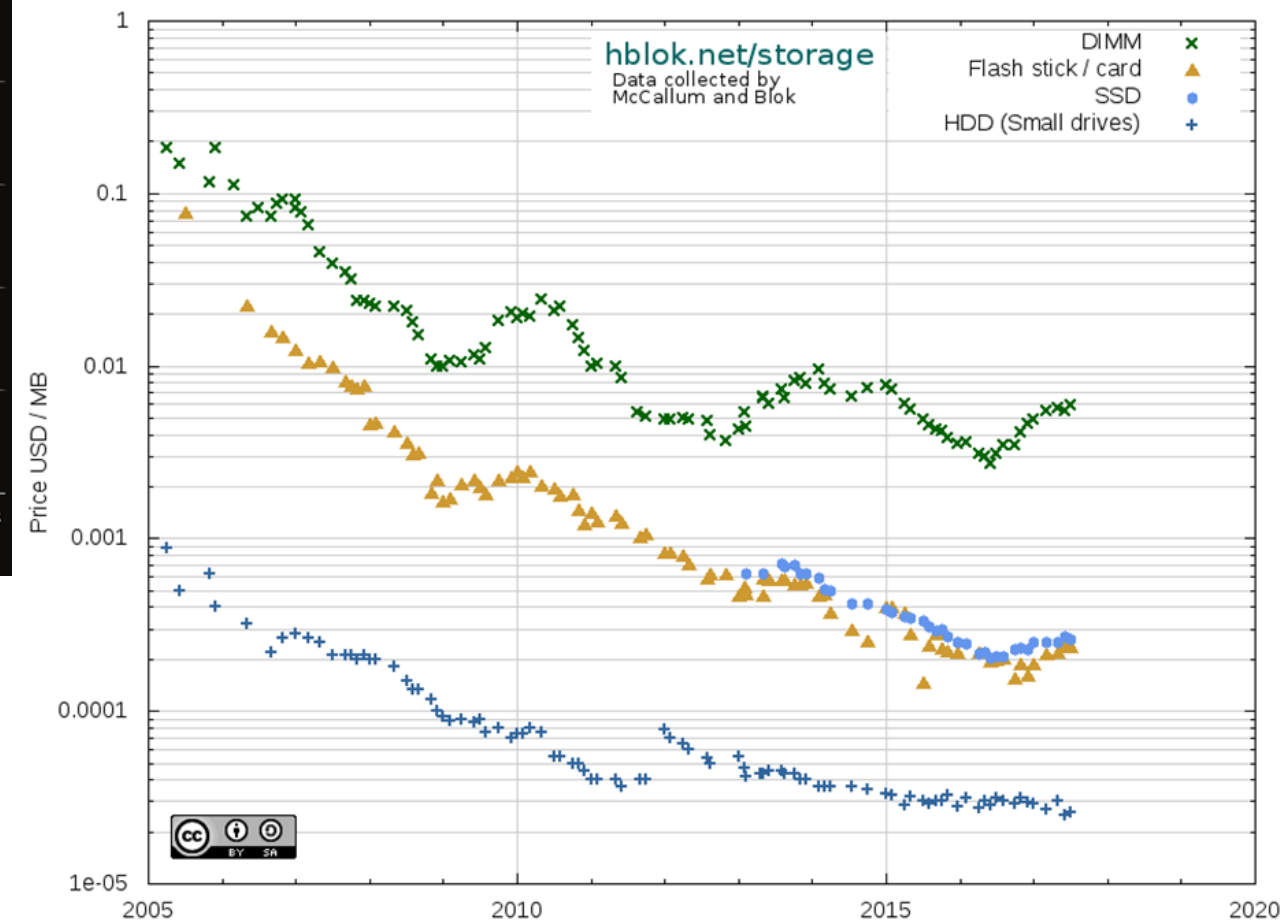
HDD vs. Flash SSD \$/TB Annual Takedown Trend

MAMR will enable continued \$/TB advantage over Flash SSDs



Solid State Disk Storage

Historical Cost of Computer Memory and Storage



Total HDD + SSD Capacity (Exabytes); SSD as % of Total

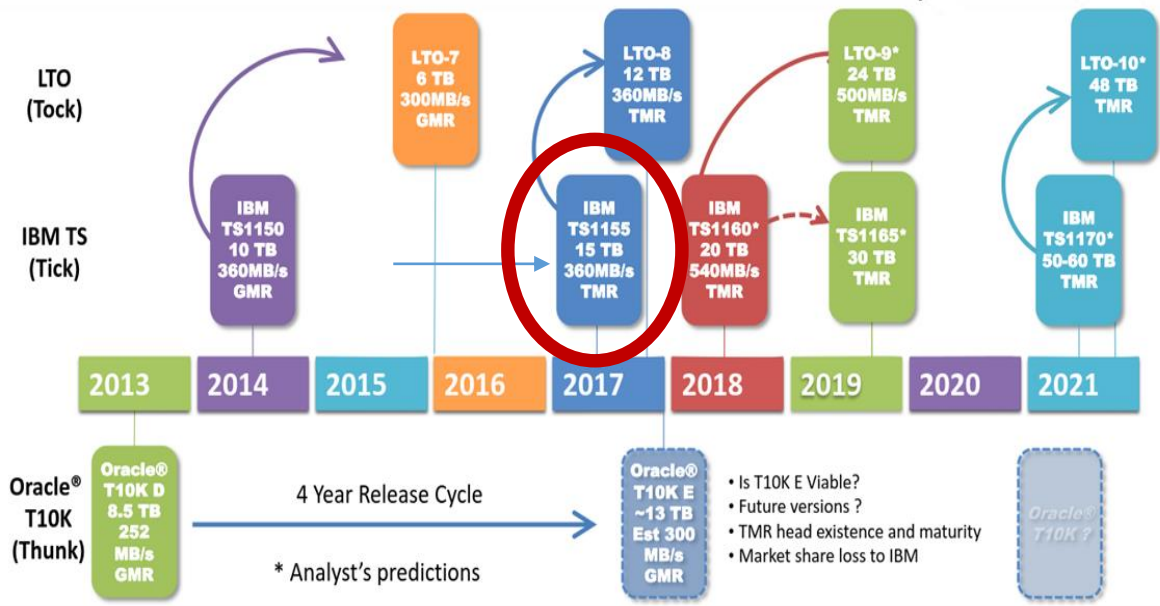


SSD versus HDD, Price difference in capacity drives will stay high For the foreseeable future

Slowdown of yearly price improvements in all areas

State of the Tape Storage Industry - Tape Technology Roadmap

TS11x0 & LTO now on a 2 year cadence

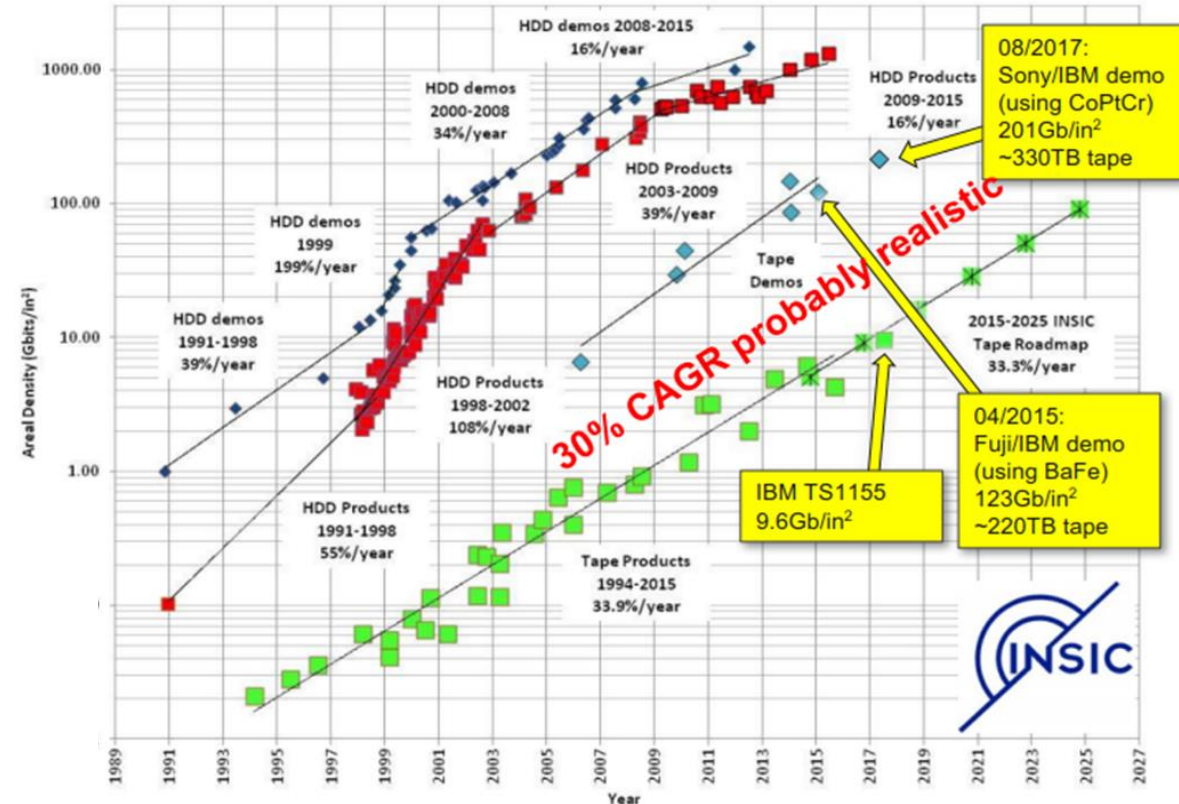


Tape Storage I

Quite some headroom for density improvements, x10 compared to HDD

Areal Density Trends

Chart provided courtesy of the Information Storage Industry Consortium (INSIC)



LTO ULTRIUM ROADMAP Addressing your storage needs

	NATIVE	COMPRESSED
LTO 12	up to 192 TB	480 TB
LTO 11	up to 96 TB	240 TB
LTO 10	up to 48 TB	120 TB
LTO 09	up to 24 TB	60 TB
LTO 08	12 TB	30 TB
LTO 07	6 TB	15 TB
LTO 06	2.5 TB	6.25 TB
LTO 05	1.5 TB	3 TB

LTO Program extends technology roadmap to 12th Generation

LTO 08 available from december 2017

LTO 07 announced and available in 2015

LTO 06 announced and available in 2012

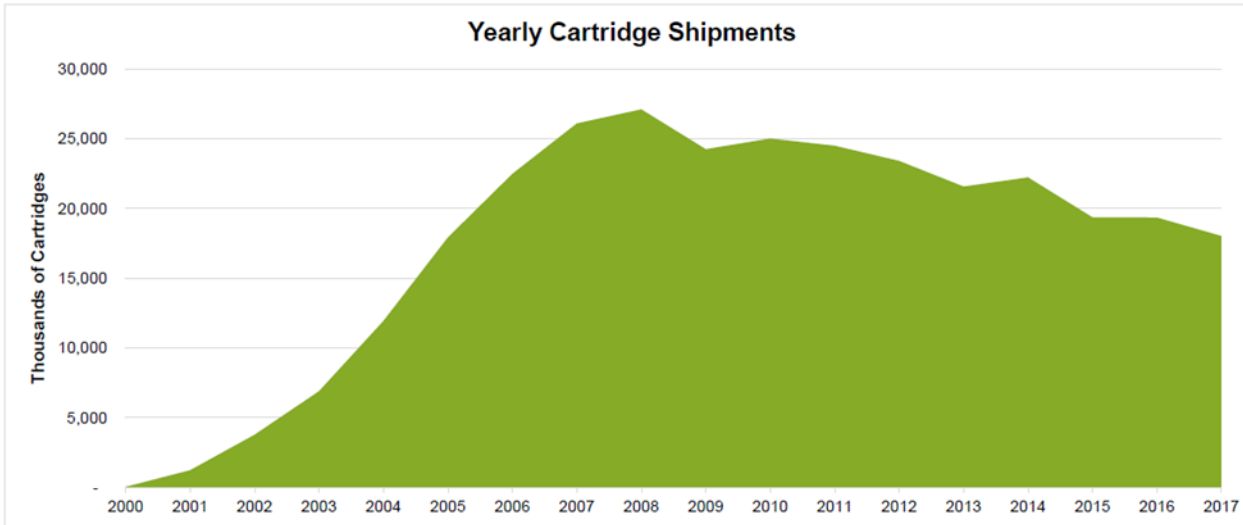
LTO 05 announced and available in 2010

Current generation
LTO-8 (12 TB) , TS1155 (15 TB)

Technology change to
Tunnel Magnetoresistive heads
(used already in HDDs)
For IBM TS1155 and LTO-8

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Unit Shipments: Calendar Year



Declining media shipment since 10 years

factor 2 decrease in #drives sold over the last 4 years

**Only two suppliers of media: Fujifilm and Sony
Fujifilm only supplier in the US (patent 'war')**

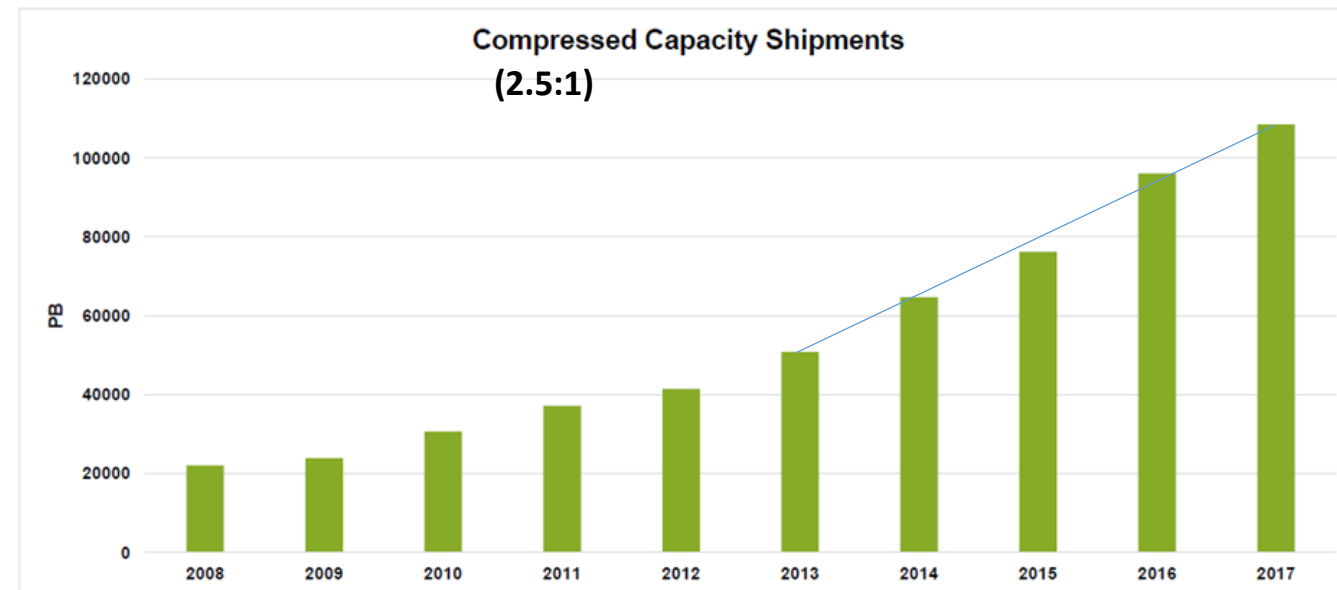
Only IBM left for LTO and Enterprise drives

Tape Storage II

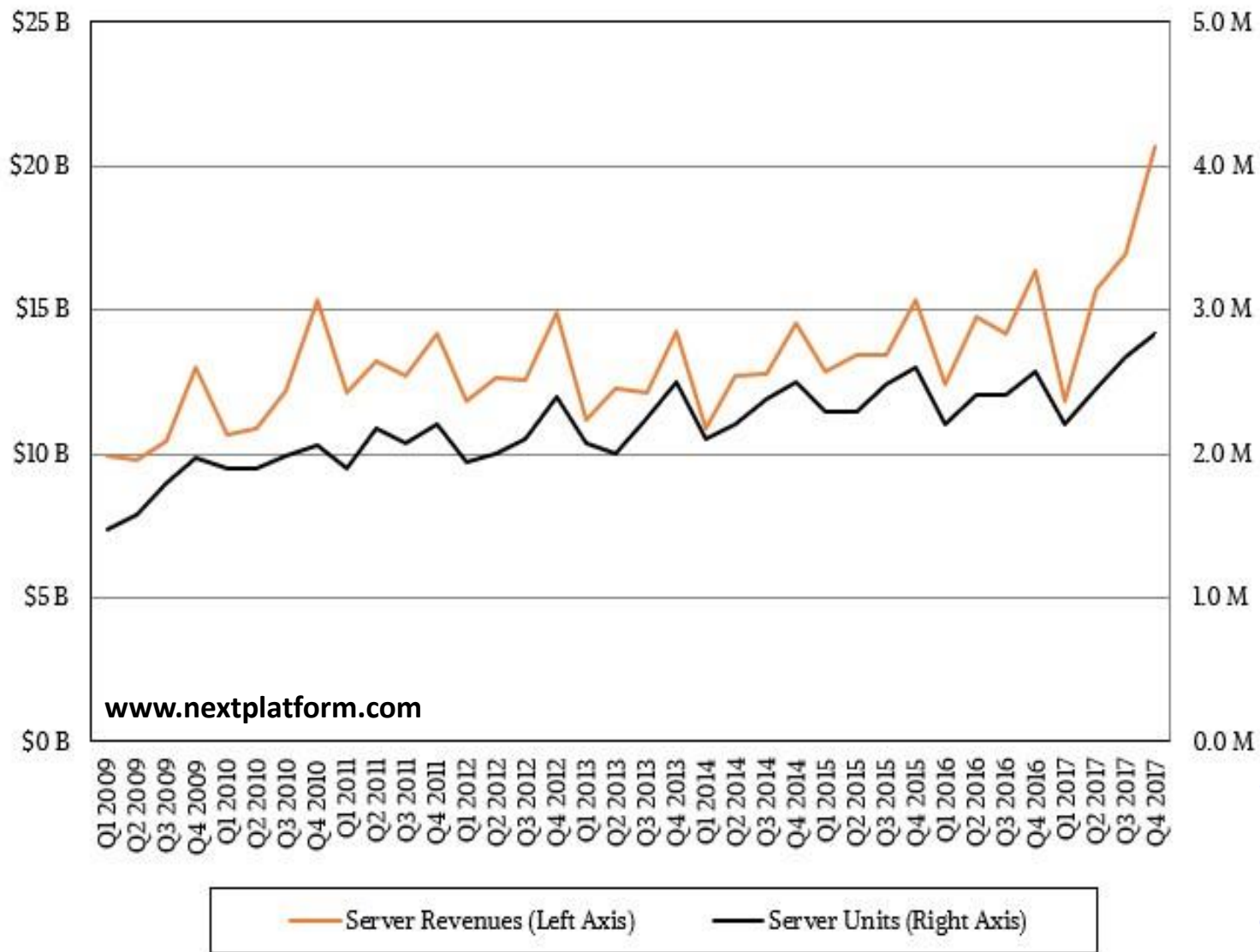
LTO tape market domination >95%
Enterprise tapes 4%

44 EB of tape media in 2017 compared to 750 EB HDD
Linear increase in EB sold per year

Total Capacity Shipped: Calendar Year



Server Market I



The total server market revenues reached 20.7 B\$ In Q4 2017 with 2.8 M servers shipped.

Large revenue jump → general price increases, memory price explosion, big Iron sales (z14 IBM), HPC/AI investment

The market is split into three parts based on the cost per server:

- 1. < 25000\$ 15.8B\$ (HEP buys < 5000 \$/server)
- 2. 25k-250k 1.9 B\$
- 3. > 250k 2.9B\$

Intel takes 85% of the revenues and ships 99.3 % of the x86 servers processors

The increase in units sold is due to several factors:

new Skylake architecture, shift from DELL/HP/etc to cheaper ODM sellers and high demand for high end machines with GPUs (> 25000\$ a piece)

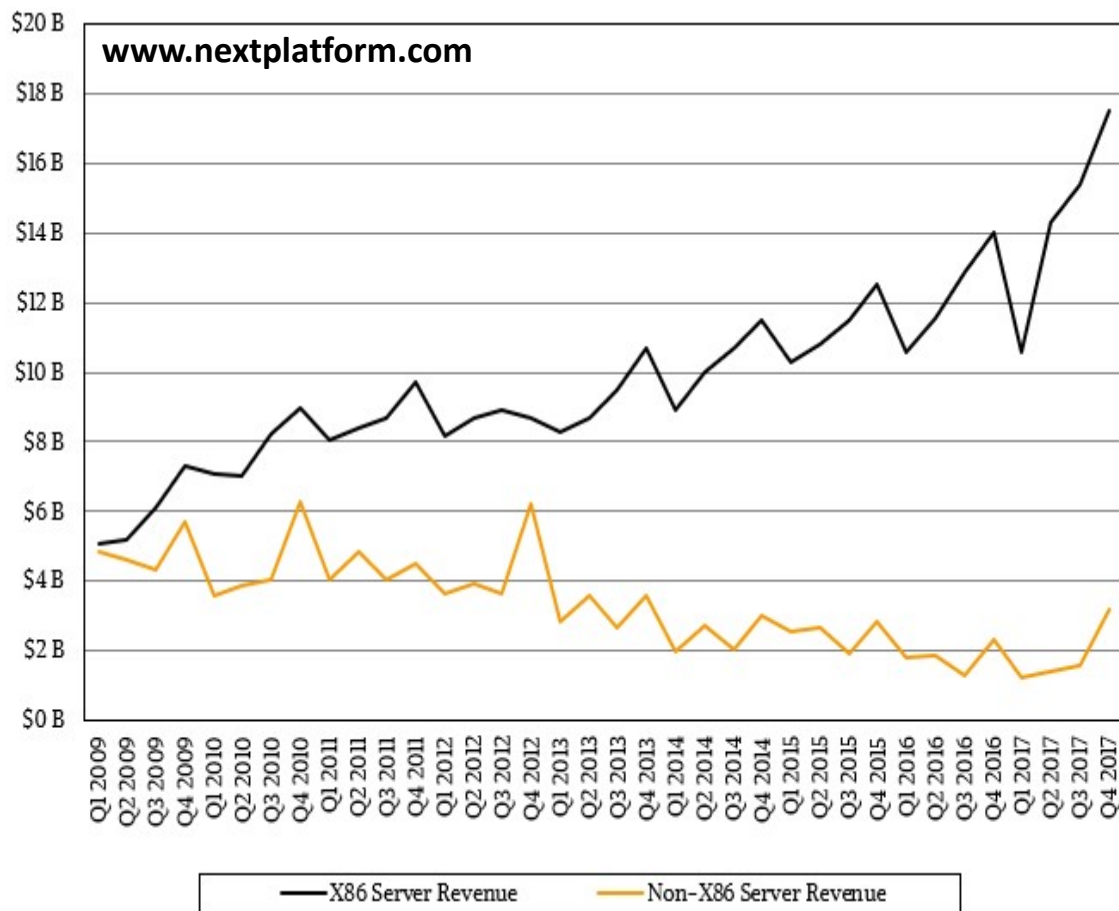
Hyperscale data centers (>100000 server) grew in 2017 from 300 to 390
Amazon, Google, Microsoft, IBM have at least 45 centers each

Server Market II

Intel x86 dominating server market, 99.3% of server units

Possible contender:

- **IBM Power9**
Aimed at high-end server and HPC/AI market (combined with Nvidia GPUs), not power efficient, 14nm process, no plans for 10/7nm
- **AMD EPYC**, low market penetration so far, 2018 will be key year
- **ShenWei 260-core processor (based on alpha, 6 Tflops SP)**
China only, TaihuLight supercomputer, public market?



ARM

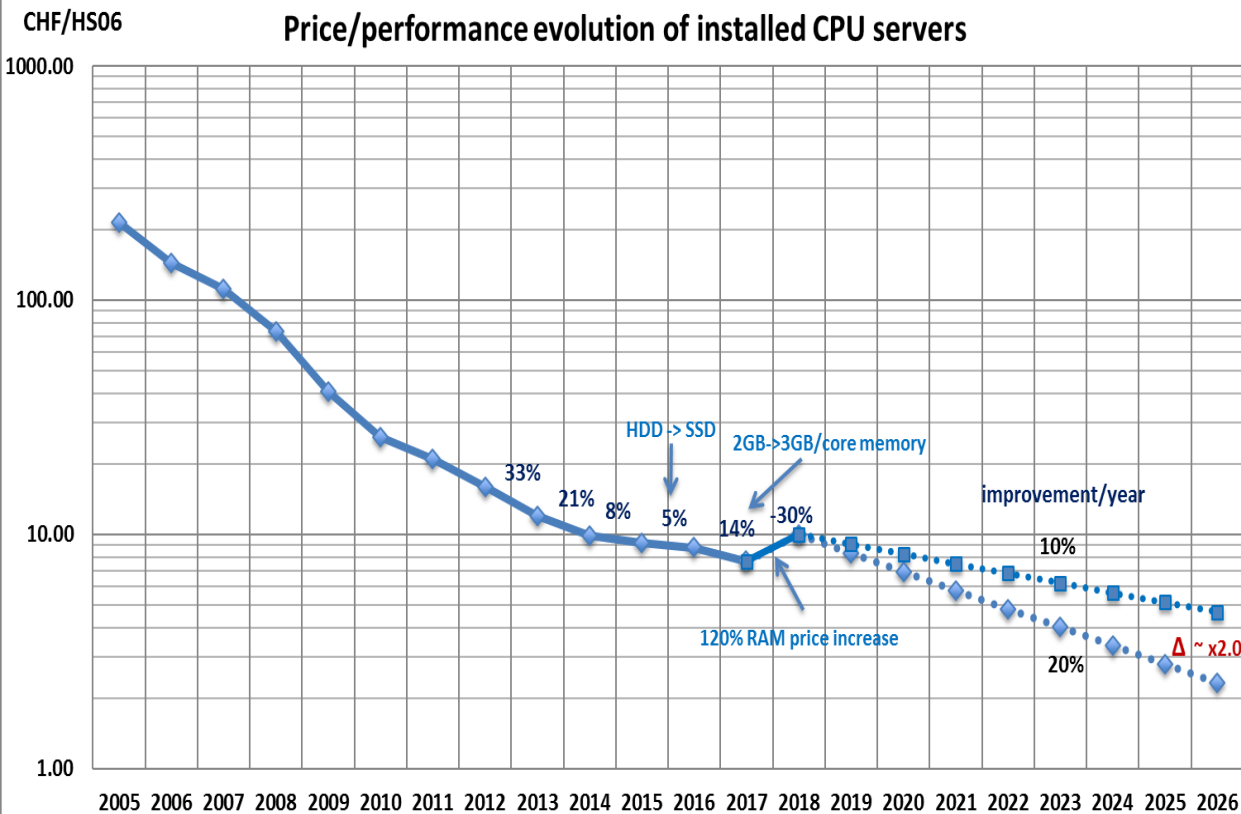
Applied Micro → Ampere : new design 32 core 3.3 GHz end 2018,

Qualcomm Centriq : 48-core, 2.6 GHz, 10nm process, first contract with cloud gaming company (but strong rumor that Qualcomm is cancelling the project.....)

Cavium → Marvell : **ThunderX2** (available in techlab, power/HS06 similar to Intel Broadwell, price/performance x2 off)

Server Cost Evolution

Disk server: very hard to estimate the REAL costs of HDDs
 e.g. there are 70 different 6TB HDD models in the market with a price difference of a factor 2.5. At CERN we saw price difference of a factor >2 between low street prices and purchase prices. more variations between 6 TB and 8TB disks

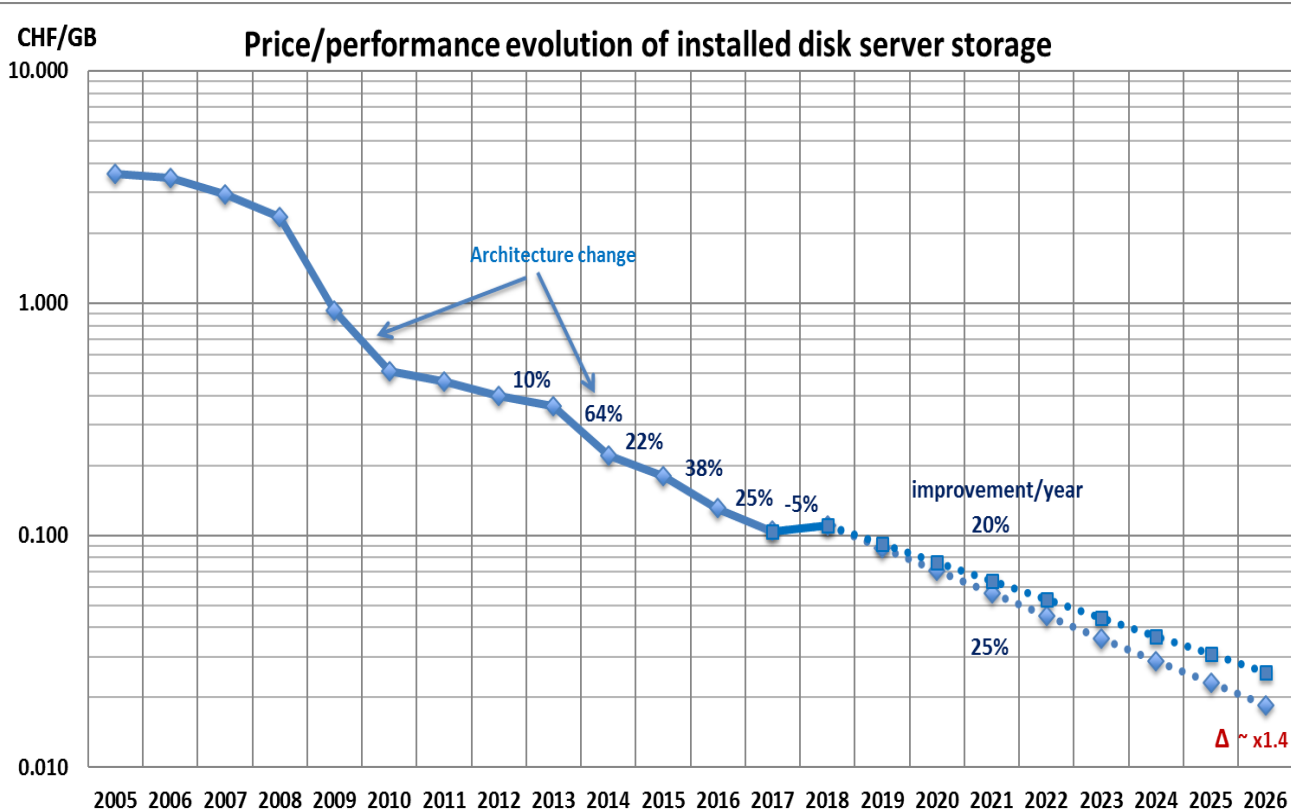


Based on CERN procurements during the last years

Current assumption:

Future CPU server price/performance improvement: 15%

Future Disk server price/space improvement: 20%



Summary

- **Technology progress per se is good, but obstacles ahead (CPU, RAM, NAND)**
- **Key computing markets in the hand of very few companies**
- **Price/performance advances are slowing down**
- **Memory prices will still increase, but major price reductions expected end 2018**
- **New processors and architectures are mainly focused on Machine Learning, highly profitable markets expected**
- **HDD still key storage for the foreseeable future, SSDs not cost effective**
- **Have to closely watch the tape development**
- **Server market still 99% Intel some competition is advancing, but not yet convincing**

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